

# MOS FIELD EFFECT TRANSISTOR $\mu PA1950$

# P-CHANNEL MOS FIELD EFFECT TRANSISTOR FOR SWITCHING

### DESCRIPTION

The  $\mu$ PA1950 is a switching device which can be driven directly by a 1.8 V power source.

This device features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

#### FEATURES

- 1.8 V drive available
- Low on-state resistance  $R_{DS(on)1} = 130 \text{ m}\Omega \text{ MAX}. (V_{GS} = -4.5 \text{ V}, \text{ ID} = -1.5 \text{ A})$   $R_{DS(on)2} = 176 \text{ m}\Omega \text{ MAX}. (V_{GS} = -3.0 \text{ V}, \text{ ID} = -1.5 \text{ A})$   $R_{DS(on)3} = 205 \text{ m}\Omega \text{ MAX}. (V_{GS} = -2.5 \text{ V}, \text{ ID} = -1.5 \text{ A})$  $R_{DS(on)4} = 375 \text{ m}\Omega \text{ MAX}. (V_{GS} = -1.8 \text{ V}, \text{ ID} = -1.0 \text{ A})$

#### **ORDERING INFORMATION**

PART NUMBER	PACKAGE	
μΡΑ1950ΤΕ <sup>Νote</sup>	SC-95 (Mini Mold Thin Type)	

Note Marking: TM

#### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

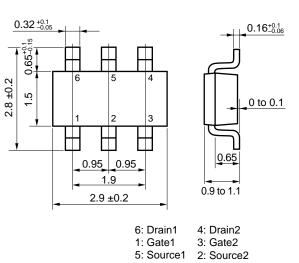
Drain to Source Voltage (Vgs = 0 V)	VDSS	-12	V
Gate to Source Voltage (VDs = 0 V)	Vgss	∓8.0	V
Drain Current (DC) (T <sub>A</sub> = 25°C)	D(DC)	∓2.5	А
Drain Current (pulse) Note1	D(pulse)	∓7.0	А
Total Power Dissipation (2unit) Note2	P <sub>T1</sub>	1.15	W
Total Power Dissipation (1unit) Note2	Рт2	0.57	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	–55 to +150	°C
<b>Notes 1.</b> PW $\leq$ 10 $\mu$ s, Duty Cycle $\leq$ 1%			

**2.** Mounted on FR-4 board,  $t \le 5$  sec.

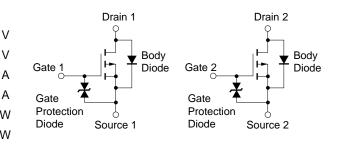
**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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#### PACKAGE DRAWING (Unit : mm)



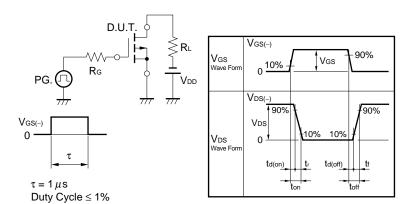
#### EQUIVALENT CIRCUIT



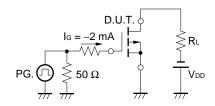
ELECTRICAL CHARACTERISTICS (TA = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = -12 V, V_{GS} = 0 V$			-10	μA
Gate Leakage Current	lgss	$V_{GS} = \mp 8.0 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$			∓10	μA
Gate Cut-off Voltage	VGS(off)	$V_{DS} = -10 V$ , $I_D = -1.0 mA$	-0.45		-1.5	V
Forward Transfer Admittance	yfs	$V_{DS} = -10 V$ , $I_D = -1.5 A$	1.0			S
Drain to Source On-state Resistance	RDS(on)1	$V_{GS} = -4.5 V$ , $I_D = -1.5 A$		105	130	mΩ
	RDS(on)2	$V_{GS} = -3.0 \text{ V}, \text{ Id} = -1.5 \text{ A}$		135	176	mΩ
	RDS(on)3	$V_{GS} = -2.5 V$ , $I_D = -1.5 A$		160	205	mΩ
	RDS(on)4	$V_{GS} = -1.8 V$ , $I_D = -1.0 A$		225	375	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = -10 V		220		pF
Output Capacitance	Coss	Vgs = 0 V		90		pF
Reverse Transfer Capacitance	Crss	f = 1.0 MHz		40		pF
Turn-on Delay Time	td(on)	$V_{DD} = -6.0 \text{ V}, \text{ ID} = -1.5 \text{ A}$		15		ns
Rise Time	tr	Vgs = -4.0 V		80		ns
Turn-off Delay Time	td(off)	Rg = 10 Ω		150		ns
Fall Time	tr			120		ns
Total Gate Charge	QG	$V_{DD} = -10 V$		1.9		nC
Gate to Source Charge	QGS	Vgs = -4.0 V		0.5		nC
Gate to Drain Charge	Qgd	ID = -2.5 A		0.7		nC
Body Diode Forward Voltage	VF(S-D)	IF = 2.5 A, VGS = 0 V		0.86		V

#### **TEST CIRCUIT 1 SWITCHING TIME**



#### **TEST CIRCUIT 2 GATE CHARGE**



PW=1 ms 10 ms

100 ms

5 s (2 units)

5 s (1 unit)

-1.5

25°C

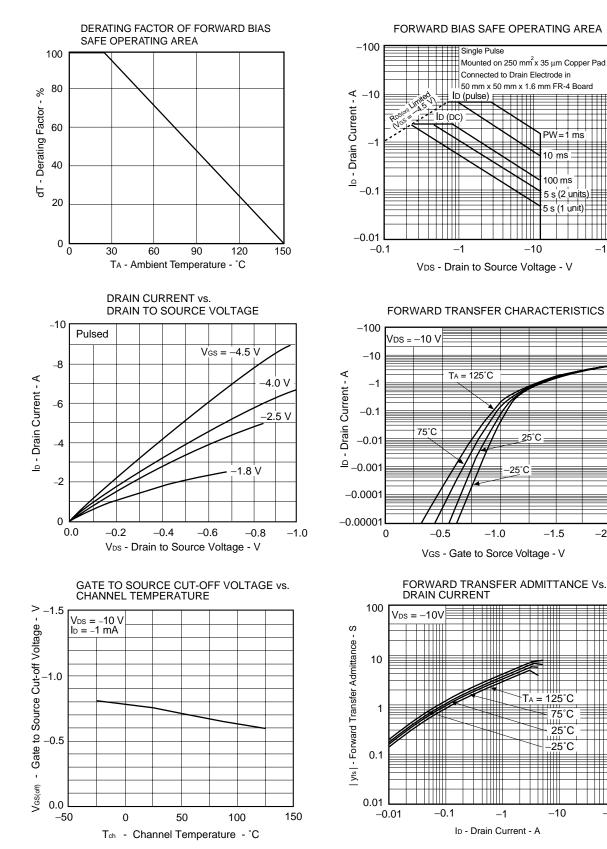
–25°C

-10

-2.0

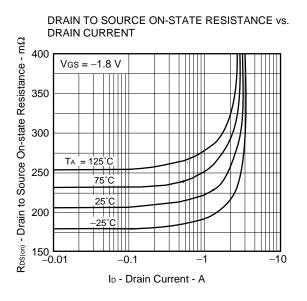
-100

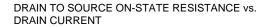
## **TYPICAL CHARACTERISTICS (TA = 25°C)**

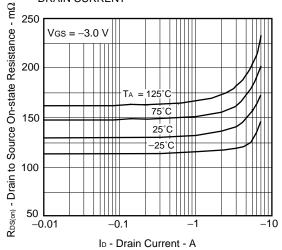


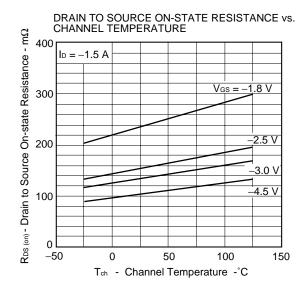
Data Sheet G15620EJ2V0DS

-100

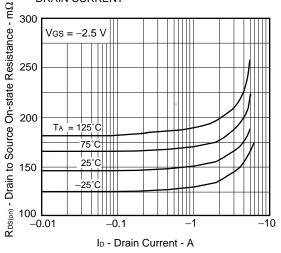




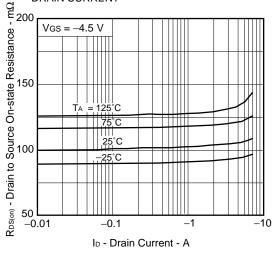


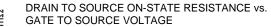


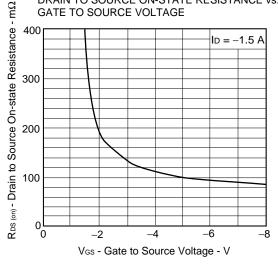
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



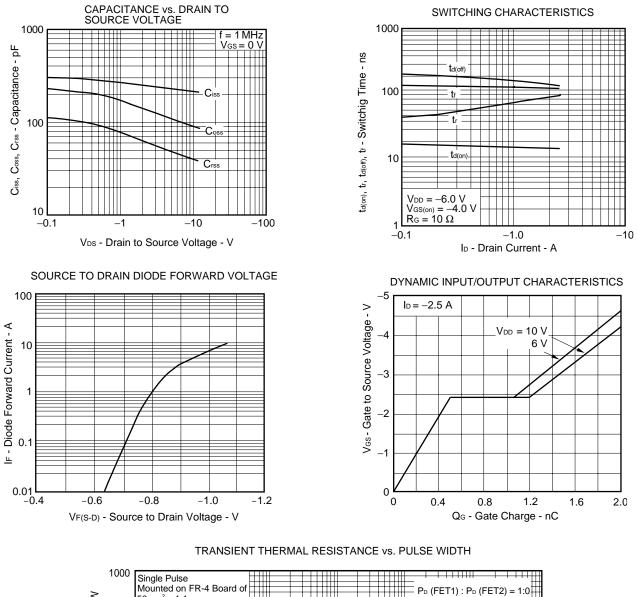
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

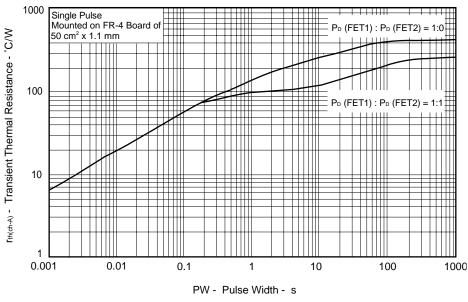






Data Sheet G15620EJ2V0DS





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